WaferSense® Auto Multi Sensor™ (AMS)

Speed vibration, leveling and humidity measurements with all-in-one measurement device. Improve yields.





Speed equipment qualification with wireless measurements

- Collect and display acceleration, vibration, leveling and humidity data.
- Monitor humidity in wafer environments.
- Use the Auto Multi Sensor with MultiView[™] and MultiReview[™] software for real-time equipment diagnostics.
- See the effects of adjustments in real-time, speeding equipment alignment and set-up.

Shorten equipment maintenance cycles with thin and lightweight wafer-like form factor.

- Thinner 3.5mm form factor provides access to more chambers.
- Operates at higher temperatures.
- Keep the process areas unexposed to the fab environment with vacuum compatible AMS.

Lower equipment maintenance expenses and enhance process uniformity with objective and reproducible data.

- Take the human element out of adjusting your equipment with objective measurements for multiple applications in one.
- Make the right adjustments time after time.
- Receive early warning for impending equipment failures and optimize your preventative maintenance plans.

Semiconductor fabs and OEMs worldwide value the accuracy, precision and versatility of the WaferSense AMS - The most efficient and effective wireless measurement device for leveling, vibration and humidity.







Save Time. Save Expense. Improve Yields.

Features*

Wireless, wafer-shaped	Available in 150mm, 200mm, 300mm, 450mm
and battery-powered Easy-to-use software	MultiView and MultiReview software included
	MultiView: Displays real-time visual feedback. Digital readout allows more precise adjustment
	MultiReview: Replays log file data for review and analysis
Highly accurate - leveling	Horizontal accuracy: +/-0.03 deg within +/- 7 deg (200 & 300mm) +/- 4 deg (450mm) from absolute Vertical accuracy: +/-0.05deg within +/-50 deg from vertical
	Horizontal resolution: +/-0.002deg within +/-14 deg. Vertical resolution: +/-0.01deg within +/- 50 deg
Reports inclination in three dimensions	x, y and vertical
Highly accurate - vibration	Reports accelerations in three directions: x, y, and z and RMS display allows quick, objective measurements.
	Operating range: +/- 2G.
Relative measurements	Zero position may be set to any reference plane within the system's operating range for easy relative measurements
Humidity accuracy	+/- 2% RH
Humidity measurements	1 Relative Humidity (RH) sensor (150mm and 200mm) 5 Relative Humidity (RH) sensors in one wafer (300mm)
Durable housing	Carbon fiber composite
Lightweight	140 grams (300mm)
Thin	3.5mm thick
Operating pressure	<10e-6 to 760 torr
Operating temperature	20 to 80 degrees C for extended periods. Up to 130 degrees C for shorter periods.
Battery-operation	Up to 4hrs. per charge, non-contact inductive charging.
WaferSense Link	Bluetooth, 2.4 GHz, USB 1.1, dimensions 92mm x 58mm x 28mm
Operating Systems	Windows 7, XP and Vista
Product components	Auto Multi Sensor measurement device, charging clean box, carrying suitcase, USB communications link module and application software
Calibration	Factory recalibration recommended annually

^{*}Preliminary Specifications Subject to Change

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